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April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

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# HD74ALVCH16827

## 20-bit Buffers / Drivers with 3-state Outputs

REJ03D0033-0400Z  
 (Previous ADE-205-140B(Z))  
 Rev.4.00  
 Oct.02.2003

### Description

The HD74ALVCH16827 is composed of two 10-bit sections with separated output enable signals. For either 10-bit buffer section, the two output enable ( $\overline{1OE1}$  and  $\overline{1OE2}$  or  $\overline{2OE1}$  and  $\overline{2OE2}$ ) inputs must both be low for the corresponding Y outputs to be active. If either output enable input is high, the outputs of that 10-bit buffer section are in the high impedance state. Active bus hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

### Features

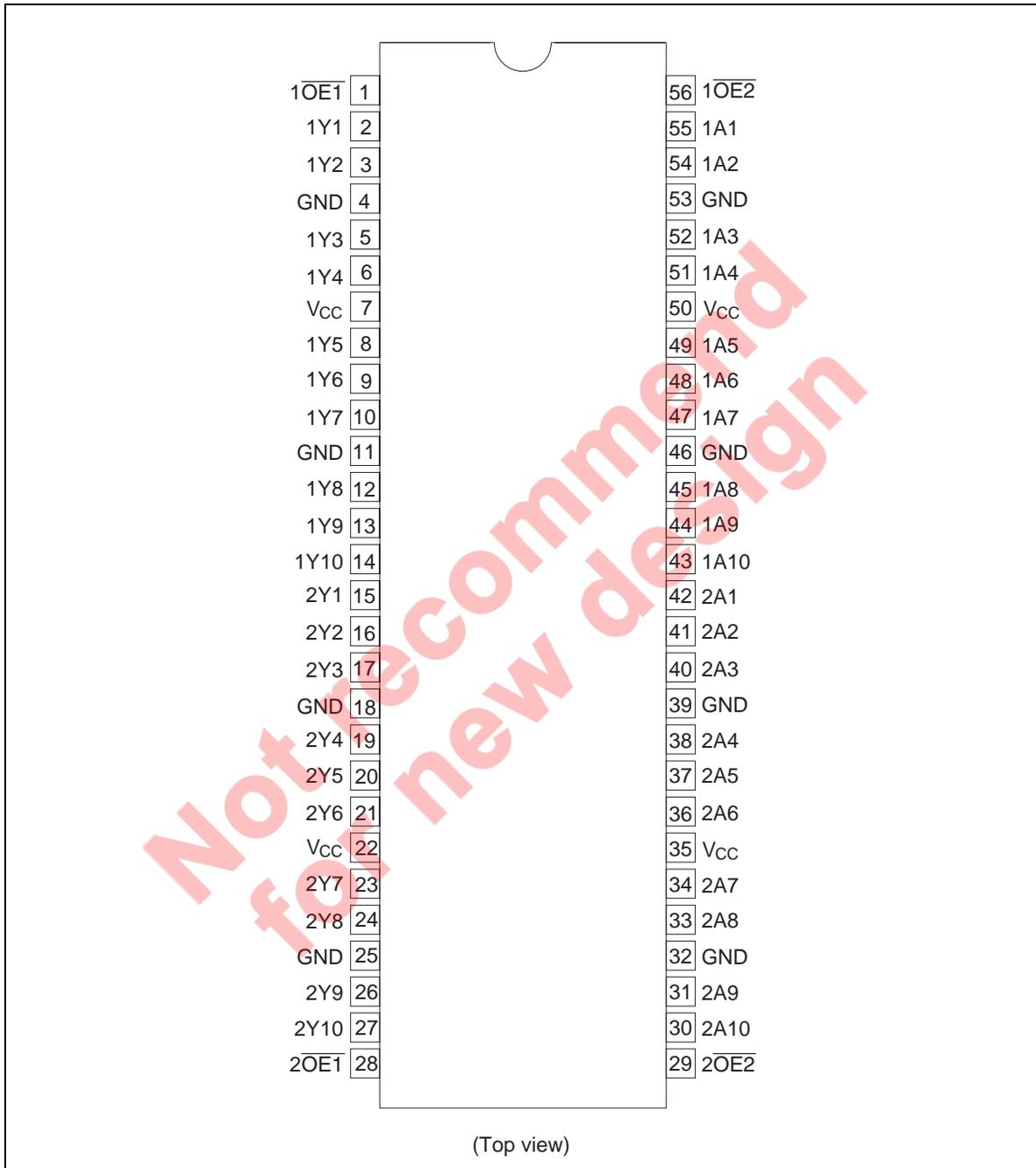
- $V_{CC} = 2.3\text{ V to }3.6\text{ V}$
- Typical  $V_{OL}$  ground bounce  $< 0.8\text{ V}$  (@ $V_{CC} = 3.3\text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- Typical  $V_{OH}$  undershoot  $> 2.0\text{ V}$  (@ $V_{CC} = 3.3\text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- High output current  $\pm 24\text{ mA}$  (@ $V_{CC} = 3.0\text{ V}$ )
- Bus hold on data inputs eliminates the need for external pullup / pulldown resistors

### Function Table

Inputs			Output Y
$\overline{OE1}$	$\overline{OE2}$	A	
L	L	L	L
L	L	H	H
H	X	X	Z
X	H	X	Z

H : High level  
 H : High level  
 X : Immaterial  
 Z : High impedance

Pin Arrangement



**Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	$V_{CC}$	-0.5 to 4.6	V	
Input voltage <sup>*1</sup>	$V_I$	-0.5 to 4.6	V	
Output voltage <sup>*1, 2</sup>	$V_O$	-0.5 to $V_{CC} + 0.5$	V	
Input clamp current	$I_{IK}$	-50	mA	$V_I < 0$
Output clamp current	$I_{OK}$	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	$I_O$	±50	mA	$V_O = 0$ to $V_{CC}$
$V_{CC}$ , GND current / pin	$I_{CC}$ or $I_{GND}$	±100	mA	
Maximum power dissipation at $T_a = 55^\circ\text{C}$ (in still air) <sup>*3</sup>	$P_T$	1	W	TSSOP
Storage temperature	$T_{stg}$	-65 to 150	°C	

Notes: Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

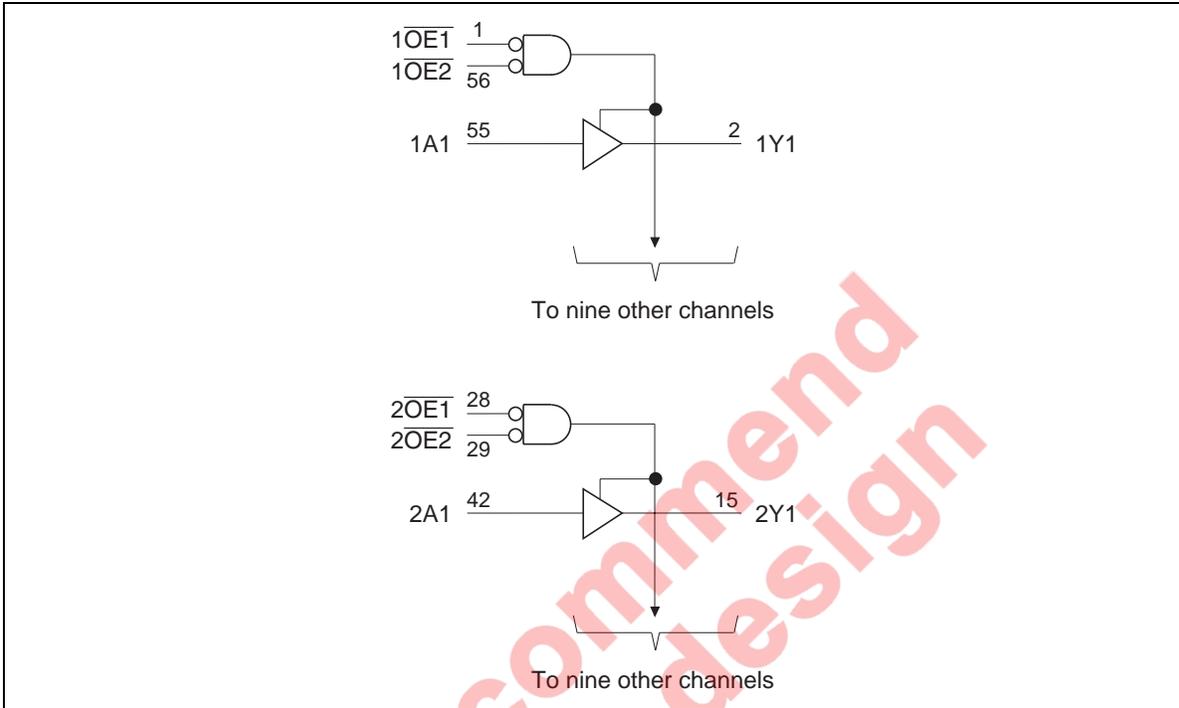
1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

**Recommended Operating Conditions**

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage	$V_{CC}$	2.3	3.6	V	
Input voltage	$V_I$	0	$V_{CC}$	V	
Output voltage	$V_O$	0	$V_{CC}$	V	
High level output current	$I_{OH}$	—	-12	mA	$V_{CC} = 2.3\text{ V}$
		—	-12		$V_{CC} = 2.7\text{ V}$
		—	-24		$V_{CC} = 3.0\text{ V}$
Low level output current	$I_{OL}$	—	12	mA	$V_{CC} = 2.3\text{ V}$
		—	12		$V_{CC} = 2.7\text{ V}$
		—	24		$V_{CC} = 3.0\text{ V}$
Input transition rise or fall rate	$\Delta t / \Delta v$	0	10	ns / V	
Operating temperature	$T_a$	-40	85	°C	

Note: Unused control inputs must be held high or low to prevent them from floating.

Logic Diagram



Not recommended  
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**Electrical Characteristics**

(Ta = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V) <sup>*1</sup>	Min	Max	Unit	Test Conditions
Input voltage	V <sub>IH</sub>	2.3 to 2.7	1.7	—	V	
		2.7 to 3.6	2.0	—		
	V <sub>IL</sub>	2.3 to 2.7	—	0.7		
		2.7 to 3.6	—	0.8		
Output voltage	V <sub>OH</sub>	Min to Max	V <sub>CC</sub> -0.2	—	V	I <sub>OH</sub> = -100 μA
		2.3	2.0	—		I <sub>OH</sub> = -6 mA, V <sub>IH</sub> = 1.7 V
		2.3	1.7	—		I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 1.7 V
		2.7	2.2	—		I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2.0 V
		3.0	2.4	—		I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2.0 V
		3.0	2.0	—		I <sub>OH</sub> = -24 mA, V <sub>IH</sub> = 2.0 V
	V <sub>OL</sub>	Min to Max	—	0.2	μA	I <sub>OL</sub> = 100 μA
		2.3	—	0.4		I <sub>OL</sub> = 6 mA, V <sub>IL</sub> = 0.7 V
		2.3	—	0.7		I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.7 V
		2.7	—	0.4		I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.8 V
		3.0	—	0.55		I <sub>OL</sub> = 24 mA, V <sub>IL</sub> = 0.8 V
Input current	I <sub>IN</sub>	3.6	—	±5	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND
	I <sub>IN (hold)</sub>	2.3	45	—		V <sub>IN</sub> = 0.7 V
		2.3	-45	—		V <sub>IN</sub> = 1.7 V
		3.0	75	—		V <sub>IN</sub> = 0.8 V
	3.0	-75	—	V <sub>IN</sub> = 2.0 V		
	3.6	—	±500	V <sub>IN</sub> = 0 to 3.6 V		
Off state output current <sup>*2</sup>	I <sub>OZ</sub>	3.6	—	±10	μA	V <sub>OUT</sub> = V <sub>CC</sub> or GND
Quiescent supply current	I <sub>CC</sub>	3.6	—	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND
	ΔI <sub>CC</sub>	3.0 to 3.6	—	750		V <sub>IN</sub> = one input at (V <sub>CC</sub> -0.6) V, other inputs at V <sub>CC</sub> or GND

Notes: 1. For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

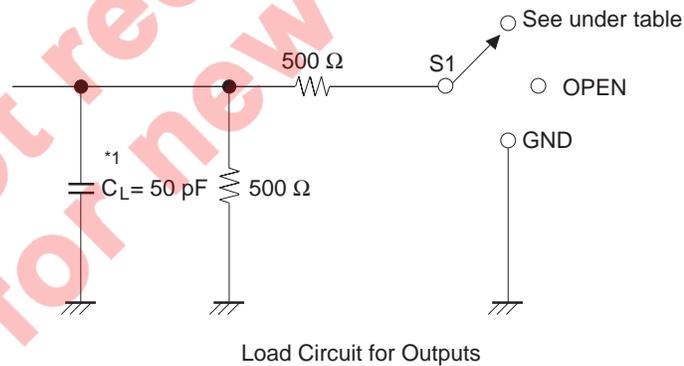
2. For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

Switching Characteristics

(Ta = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Typ	Max	Unit	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub>	2.5±0.2	1.0	—	4.1	ns	A	Y
	t <sub>PHL</sub>	2.7	—	—	3.9			
		3.3±0.3	1.0	—	3.4			
Output enable time	t <sub>ZH</sub>	2.5±0.2	1.0	—	6.0	ns	OE	Y
	t <sub>ZL</sub>	2.7	—	—	5.7			
		3.3±0.3	1.0	—	4.7			
Output disable time	t <sub>HZ</sub>	2.5±0.2	1.9	—	5.6	ns	OE	Y
	t <sub>LZ</sub>	2.7	—	—	4.9			
		3.3±0.3	1.3	—	4.5			
Input capacitance	C <sub>IN</sub>	3.3	—	3.5	—	pF	Control inputs	
		3.3	—	6.0	—		Data inputs	
Output capacitance	C <sub>O</sub>	3.3	—	7.5	—	pF	Outputs	

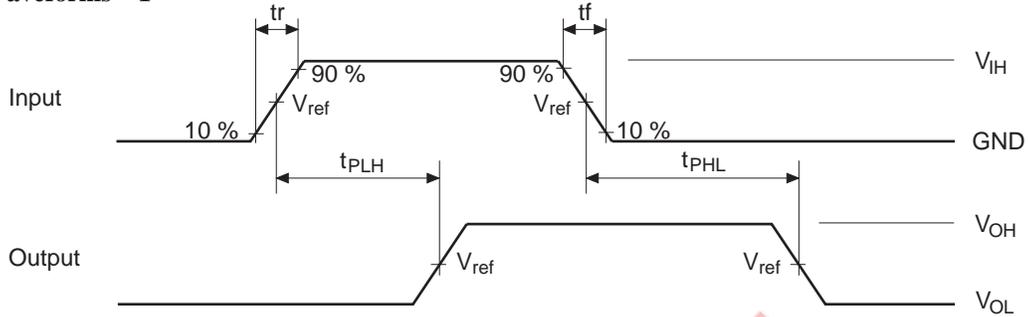
• Test Circuit



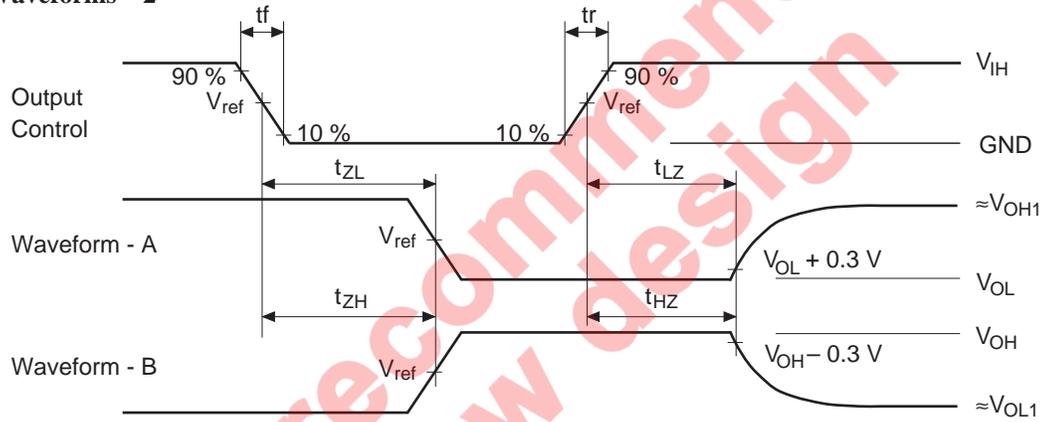
Symbol	V <sub>CC</sub> =2.5±0.2 V	V <sub>CC</sub> = 2.7 V, 3.3±0.3 V <sup>1</sup>
t <sub>PLH</sub> / t <sub>PHL</sub>	OPEN	OPEN
t <sub>ZH</sub> / t <sub>HZ</sub>	GND	GND
t <sub>ZL</sub> / t <sub>LZ</sub>	4.6 V	6.0 V

Note: 1. C<sub>L</sub> includes probe and jig capacitance.

• Waveforms – 1



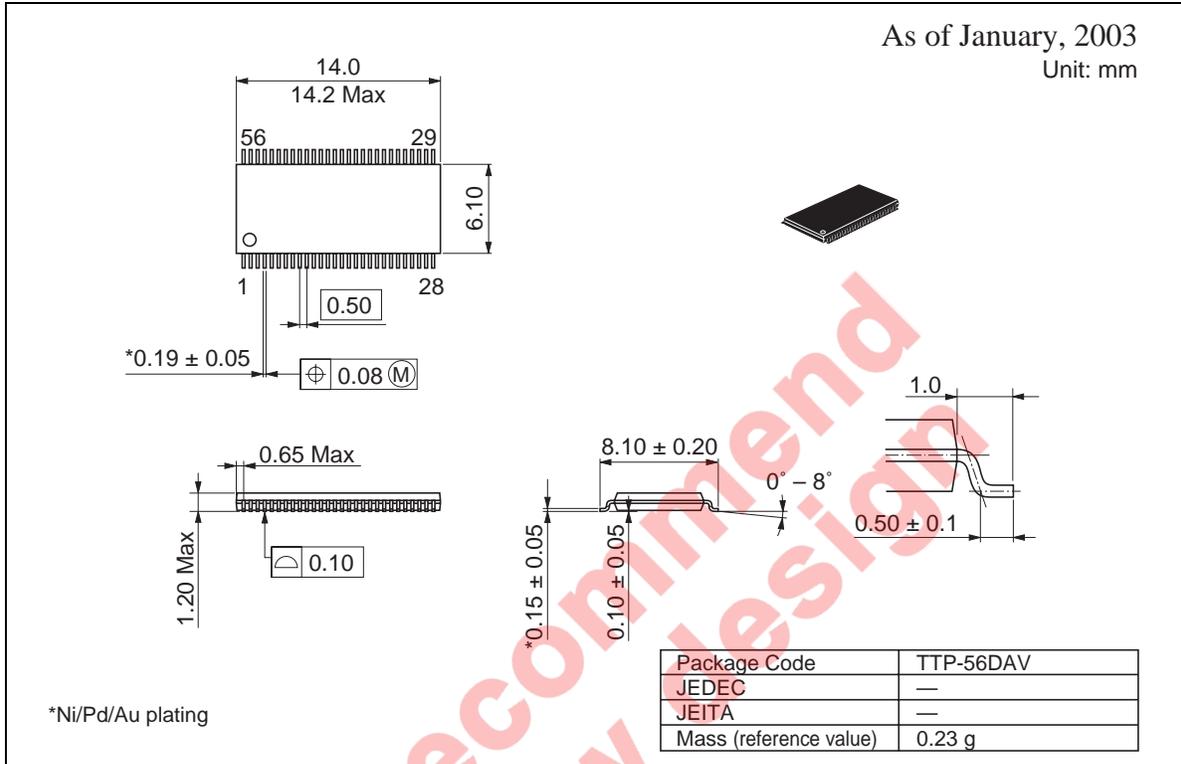
• Waveforms – 2



TEST	$V_{CC}=2.5\pm 0.2V$	$V_{CC} = 2.7V, 3.3\pm 0.3V$
$V_{IH}$	2.3 V	2.7 V
$V_{ref}$	1.2 V	1.5 V
$V_{OH1}$	2.3 V	3.0 V
$V_{OL1}$	GND	GND

- Notes:
1. All input pulses are supplied by generators having the following characteristics:  
 $PRR \leq 10 \text{ MHz}$ ,  $Z_o = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  2. Waveform – A is for an output with internal conditions such that the output is low except when disabled by the output control.
  3. Waveform – B is for an output with internal conditions such that the output is high except when disabled by the output control.
  4. The output are measured one at a time with one transition per measurement.

Package Dimensions



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